

**IN THE CLAIMS:**

1. (Currently Amended) A thermoconductive curable liquid polymer composition comprising:

(A) a curable liquid polymer;

(B) a filler made from a thermally-elongatable shape memory alloy comprising Cu-Zn-Al memory alloy filler; and

(C) a thermoconductive filler comprising alumina, with the proviso that component (C) differs from component (B).

2. (Original) The thermoconductive curable liquid polymer composition of claim 1, where component (B) has a coil shape.

3. (Cancelled).

4. (Original) The thermoconductive curable liquid polymer composition of Claim 1, wherein said component (A) is a curable liquid epoxy resin.

5. (Currently Amended) The thermoconductive curable liquid polymer composition of claim 1, where said component (A) comprises a curable liquid silicone.

6. (Currently Amended) The thermoconductive curable liquid polymer composition of claim 5, where ~~the~~said curable liquid silicone is a liquid silicone composition curable by means of an addition reaction.

7. (Currently Amended) The thermoconductive curable liquid polymer composition of claim 6, where said component (A) comprises:

- (a) 100 parts by weight of a liquid organopolysiloxane having at least two alkenyl groups per molecule;
- (b) 0.001 to 100 parts by weight of a liquid organopolysiloxane having at least two silicon-bonded hydrogen atoms per molecule; and
- (c) a hydrosilylation reaction metal catalyst, which in terms of weight units contains metal atoms in an amount of 0.01 to 1,000 ppm based on the weight of the composition.

8. (Currently Amended) The thermoconductive curable liquid polymer composition of claim 1, where ~~the~~said component (A) is present in an amount of 2.0 to 70 wt%, ~~the~~said component (B) is present in an amount of 0.01 to 30 wt%, and ~~the~~said component (C) is present in an amount of 30 to 98 wt% in the composition of the invention.

9. (Currently Amended) The thermoconductive curable liquid polymer composition of claim 1, where ~~the~~said component (A) is present in an amount of 5.0 to 50 wt%, ~~the~~said

component (B) is present in an amount of 0.1 to 20 wt%, and ~~the~~said component (C) is present in an amount of 50 to 95 wt% in the composition of the invention.

Claims 10-27. (Cancelled).

28. (New) A thermoconductive curable liquid polymer composition comprising:

- (A) a curable liquid polymer comprising a curable liquid silicone;
- (B) a filler made from a thermally-elongatable shape memory alloy; and
- (C) a thermoconductive filler, with the proviso that component (C) differs from component (B).

29. (New) The thermoconductive curable liquid polymer composition of claim 28, where component (B) has a coil shape.

30. (New) The thermoconductive curable liquid polymer composition of claim 28, where said curable liquid silicone is a liquid silicone composition curable by means of an addition reaction.

31. (New) The thermoconductive curable liquid polymer composition of claim 30, where said component (A) comprises:

- (a) 100 parts by weight of a liquid organopolysiloxane having at least two alkenyl groups per molecule;

- (b) 0.001 to 100 parts by weight of a liquid organopolysiloxane having at least two silicon-bonded hydrogen atoms per molecule; and
- (c) a hydrosilylation reaction metal catalyst, which in terms of weight units contains metal atoms in an amount of 0.01 to 1,000 ppm based on the weight of the composition.

32. (New) The thermoconductive curable liquid polymer composition of claim 28, where said component (A) is present in an amount of 2.0 to 70 wt%, said component (B) is present in an amount of 0.01 to 30 wt%, and said component (C) is present in an amount of 30 to 98 wt% in the composition of the invention.

33. (New) The thermoconductive curable liquid polymer composition of claim 1, where said component (A) is present in an amount of 5.0 to 50 wt%, said component (B) is present in an amount of 0.1 to 20 wt%, and said component (C) is present in an amount of 50 to 95 wt% in the composition of the invention.